

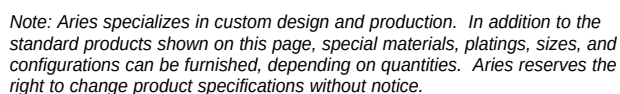


- Convert surface mount QFP packages to a 13 x 13 PGA footprint.
- Reduce costs by using less expensive QFP packages to replace PGA footprints in existing designs.
- Pins are mechanically fastened and soldered to board using Aries' patented process, creating a reliable electrical connection and rugged contact.
- Consult factory for panelized form or for mounting of con-signed chips.

- Adapter body is black FR-4 with 1 ounce minimum Copper traces.
- Pads are bare Copper protected with Entek® by Enthone to eliminate coplanarity concerns and solder bridges associated with hot air solder leveling.
- Pins are Brass Alloy 360 1/2 hard per UNS C36000 ASTM-B16-85.
- Pin plating is 200µ [5.08µm] min. 93/7 Tin/Lead per MIL-P-81728 over 100µ [2.54µm] min. Nickel per QQ-N-290.
- Operating temperature=221°F [105°C].

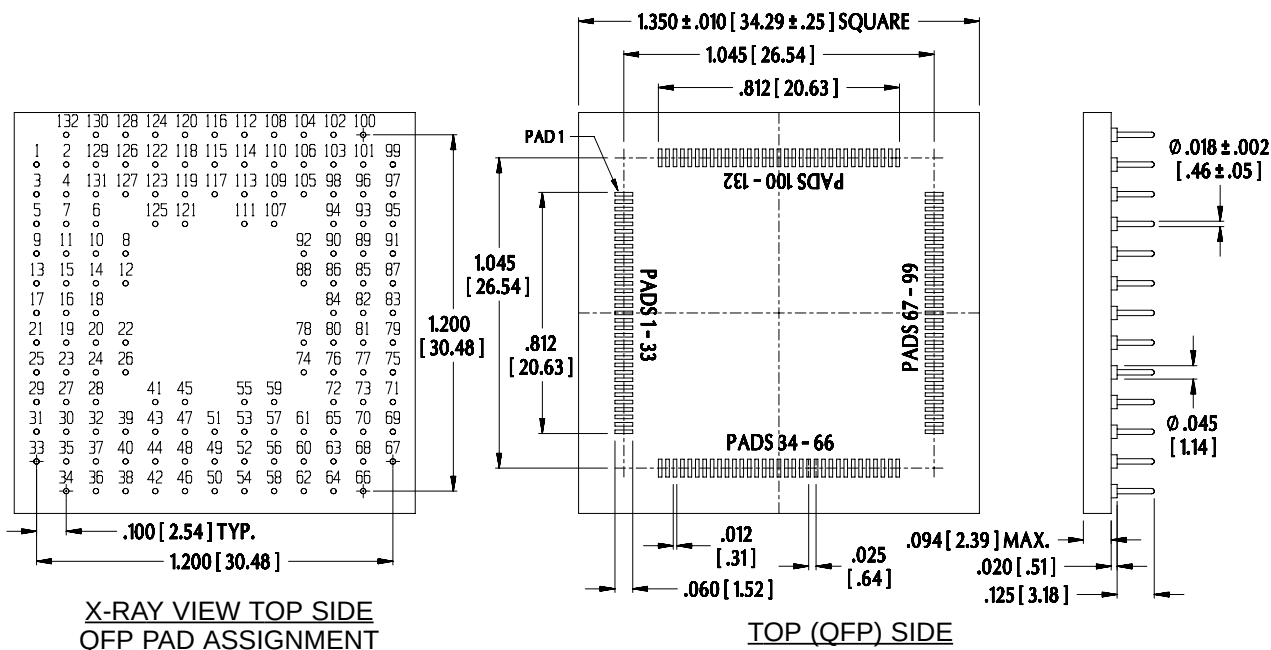
- Suggested PCB hole size = $.028 \pm .003$ [$.71 \pm .08$] dia.
- Will plug into standard PGA sockets.

Row-to-row: $\pm .003$ [$\pm .08$]
 Pin-to-pin: $\pm .003$ [$\pm .08$] non-cumulative
 All others: $\pm .005$ [.13] unless otherwise specified



95-132125-P for panelized form
when ordering

Specify Part Number 132-PGM13072-30
for wire wrap PGA socket



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